

PS9317L, PS9317L2

R08DS0135EJ0500

Rev.5.00

Oct 30, 2015

HIGH CMR, 10 Mbps, OPEN COLLECTOR OUTPUT TYPE,
8 mm CREEPAGE 6-PIN SDIP PHOTOCOUPLER

DESCRIPTION

The PS9317L and PS9317L2 are optical coupled high-speed, active low type isolators containing a GaAlAs LED on the input side and a photodiode and a signal processing circuit on the output side on one chip.

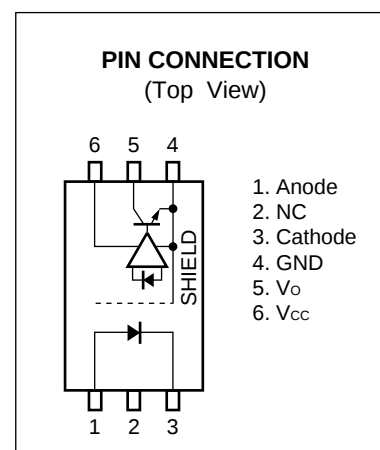
The PS9317L and PS9317L2 are designed specifically for high common mode transient immunity (CMR) and low pulse width distortion.

The PS9317L is lead bending type (Gull-wing) for surface mounting.

The PS9317L2 is lead bending type for long creepage distance (Gull-wing) for surface mount.

FEATURES

- Pulse width distortion ($|t_{PHL} - t_{PLH}| = 35 \text{ ns MAX.}$)
- High common mode transient immunity ($CM_H, CM_L = \pm 15 \text{ kV}/\mu\text{s MIN.}$)
- Half size of 8-pin DIP
- Long creepage distance (8 mm MIN. : PS9317L2)
- High-speed (10 Mbps)
- High isolation voltage ($BV = 5\,000 \text{ Vr.m.s.}$)
- Open collector output
- Pb-Free product
- Safety standards
 - UL approved: No. E72422
 - CSA approved: No. CA 101391 (CA5A, CAN/CSA-C22.2 60065, 60950)
 - DIN EN 60747-5-5 (VDE 0884-5) approved (Option)



APPLICATIONS

- Measurement equipment
- PDP
- FA Network

TRUTH TABLE

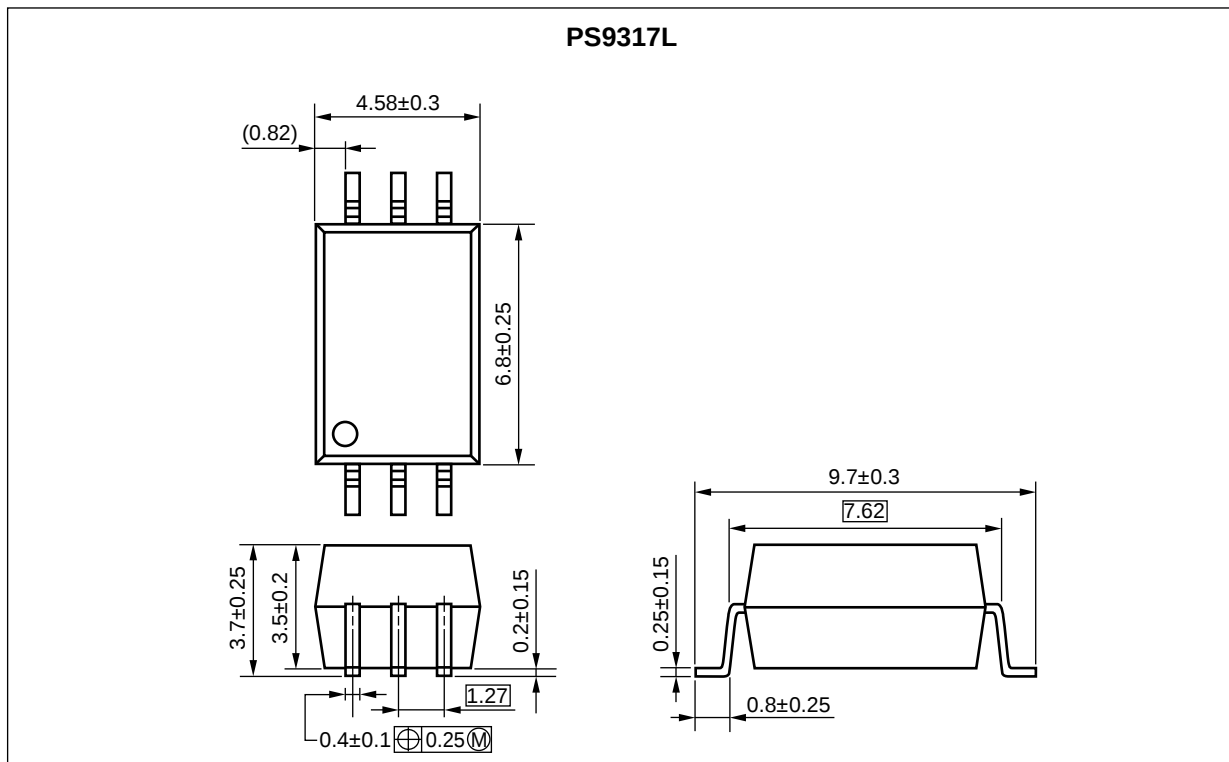
LED	Output
ON	L
OFF	H

The mark <R> shows major revised points.

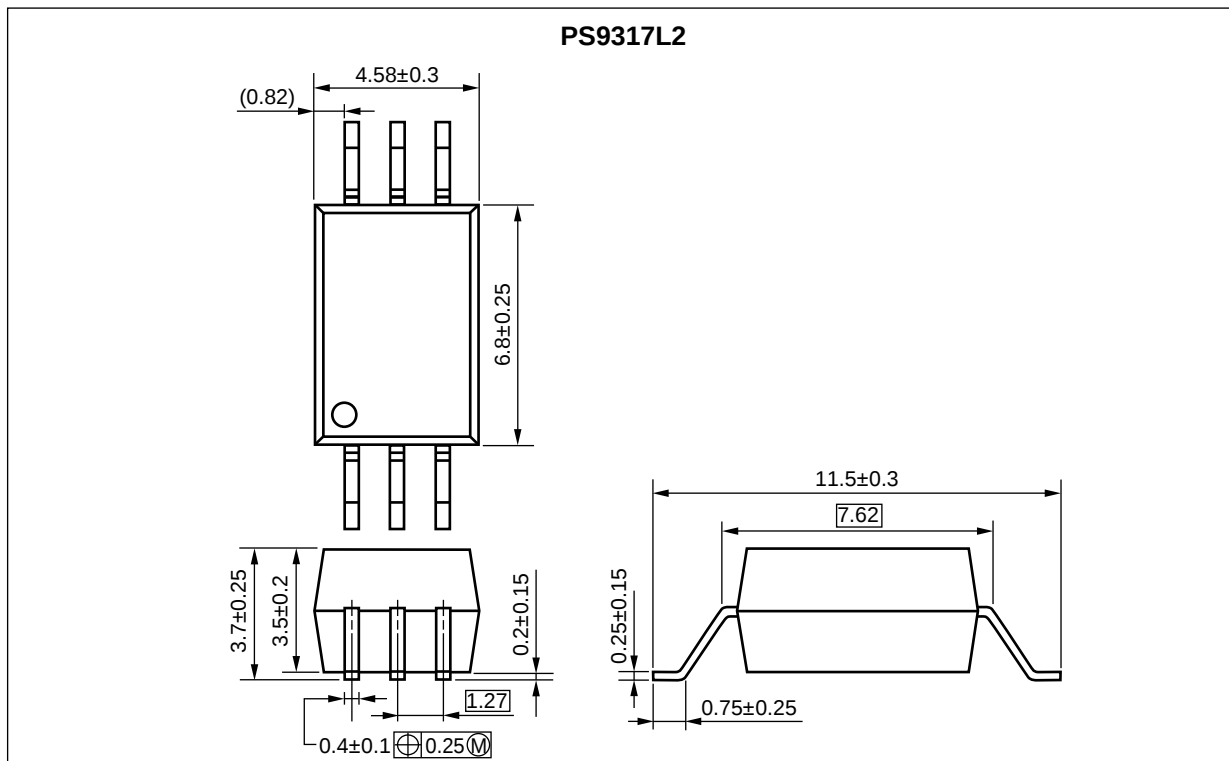
The revised points can be easily searched by copying an "<R>" in the PDF file and specifying it in the "Find what:" field.

PACKAGE DIMENSIONS (UNIT: mm)

Lead Bending Type (Gull-wing) For Surface Mount



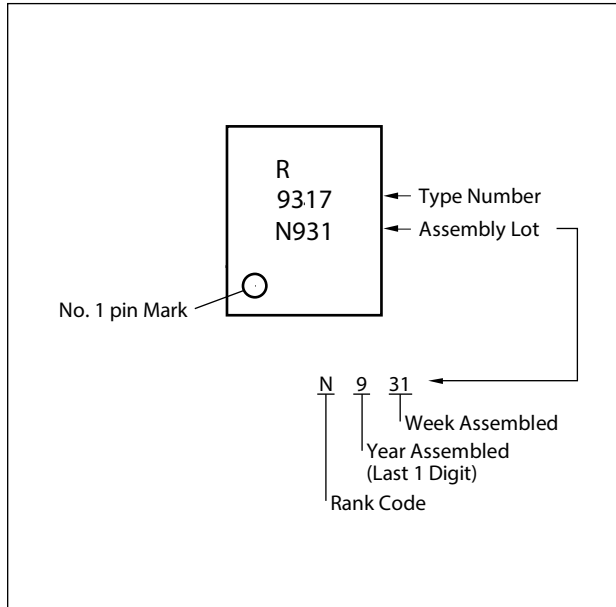
Lead Bending Type For Long Creepage Distance (Gull-wing) For Surface Mount



PHOTOCOUPLER CONSTRUCTION

Parameter	PS9317L	PS9317L2
Air Distance (MIN.)	7 mm	8 mm
Outer Creepage Distance (MIN.)	7 mm	8 mm
Isolation Distance (MIN.)	0.4 mm	0.4 mm

MARKING EXAMPLE



ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number ^{*1}
PS9317L	PS9317L-AX	Pb-Free (Ni/Pd/Au)	20 pcs (Tape 20 pcs cut)	Standard products (UL, CSA approved)	PS9317L
PS9317L-E3	PS9317L-E3-AX		Embossed Tape 2 000 pcs/reel		
PS9317L2	PS9317L2-AX		20 pcs (Tape 20 pcs cut)	UL, CSA approved DIN EN 60747-5-5 (VDE 0884-5): 2011-11 approved (Option)	PS9317L2
PS9317L2-E3	PS9317L2-E3-AX		Embossed Tape 2 000 pcs/reel		
PS9317L-V	PS9317L-V-AX		20 pcs (Tape 20 pcs cut)	UL, CSA approved DIN EN 60747-5-5 (VDE 0884-5): 2011-11 approved (Option)	PS9317L
PS9317L-V-E3	PS9317L-V-E3-AX		Embossed Tape 2 000 pcs/reel		
PS9317L2-V	PS9317L2-V-AX		20 pcs (Tape 20 pcs cut)		PS9317L2
PS9317L2-V-E3	PS9317L2-V-E3-AX		Embossed Tape 2 000 pcs/reel		

Note: ^{*1}. For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current*1	I_F	20	mA
	Reverse Voltage	V_R	5	V
Detector	Supply Voltage	V_{CC}	7	V
	Output Voltage	V_O	7	V
	Output Current	I_O	25	mA
	Power Dissipation*2	P_C	40	mW
Isolation Voltage*3		BV	5 000	Vr.m.s.
Operating Ambient Temperature		T_A	-40 to +85	$^\circ\text{C}$
Storage Temperature		T_{stg}	-55 to +125	$^\circ\text{C}$

Notes: *1. Reduced to 0.3 mA/ $^\circ\text{C}$ at $T_A = 65^\circ\text{C}$ or more.

*2. Applies to output pin V_O (collector pin). Reduced to 1.5 mW/ $^\circ\text{C}$ at $T_A = 65^\circ\text{C}$ or more.

*3. AC voltage for 1 minute at $T_A = 25^\circ\text{C}$, RH = 60% between input and output.
Pins 1-3 shorted together, 4-6 shorted together.

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Low Level Input Voltage	V_{FL}	0		0.8	V
High Level Input Current	I_{FH}	6		12	mA
Supply Voltage	V_{CC}	4.5	5.0	5.5	V
TTL ($R_L = 1\text{ k}\Omega$, loads)	N			5	
Pull-up Resistor	R_L	330		4 k	Ω

ELECTRICAL CHARACTERISTICS ($T_A = -40$ to $+85^\circ\text{C}$, unless otherwise specified)

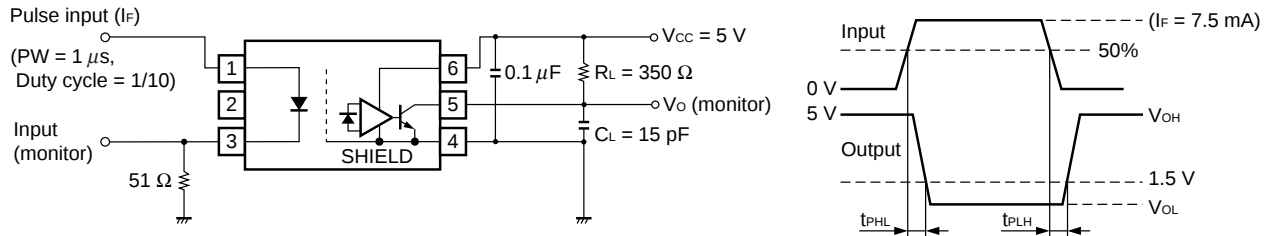
	Parameter	Symbol	Conditions	MIN.	TYP.*1	MAX.	Unit
Diode	Forward Voltage	V_F	$I_F = 10\text{ mA}$, $T_A = 25^\circ\text{C}$	1.2	1.56	1.9	V
	Reverse Current	I_R	$V_R = 3\text{ V}$, $T_A = 25^\circ\text{C}$			10	μA
	Terminal Capacitance	C_t	$V = 0\text{ V}$, $f = 1\text{ MHz}$, $T_A = 25^\circ\text{C}$		30		pF
Detector	High Level Output Current	I_{OH}	$V_{CC} = V_O = 5.5\text{ V}$, $V_F = 0.8\text{ V}$		1	100	μA
	Low Level Output Voltage*2	V_{OL}	$V_{CC} = 5.5\text{ V}$, $I_F = 5\text{ mA}$, $I_{OL} = 13\text{ mA}$		0.16	0.6	V
	High Level Supply Current	I_{CCH}	$V_{CC} = 5.5\text{ V}$, $I_F = 0\text{ mA}$, $V_O = \text{open}$		3.5	7	mA
	Low Level Supply Current	I_{CCL}	$V_{CC} = 5.5\text{ V}$, $I_F = 10\text{ mA}$, $V_O = \text{open}$		6.5	10	mA
Coupled	Threshold Input Current (H $\rightarrow$ L)	I_{FHL}	$V_{CC} = 5\text{ V}$, $V_O = 0.8\text{ V}$, $R_L = 350\ \Omega$		2	5	mA
	Isolation Resistance	R_{I-O}	$V_{I-O} = 1\text{ kV}_{DC}$, $R_H = 40$ to 60% , $T_A = 25^\circ\text{C}$	10^{11}			Ω
	Isolation Capacitance	C_{I-O}	$V = 0\text{ V}$, $f = 1\text{ MHz}$, $T_A = 25^\circ\text{C}$		0.7		pF
	Propagation Delay Time (H $\rightarrow$ L)*3	t_{PHL}	$V_{CC} = 5\text{ V}$, $R_L = 350\ \Omega$, $C_L = 15\text{ pF}$, $I_F = 7.5\text{ mA}$, $V_{THHL} = V_{THLH} = 1.5\text{ V}$		40	75	ns
	Propagation Delay Time (L $\rightarrow$ H)*3	t_{PLH}			35	75	
	Rise Time	t_r			20		
	Fall Time	t_f			5		
	Pulse Width Distortion (PWD)	$ t_{PHL} - t_{PLH} $			5	35	
	Propagation Delay Skew	t_{PSK}				40	
	Common Mode Transient Immunity at High Level Output*4	CM_H	$V_{CC} = 5\text{ V}$, $R_L = 350\ \Omega$, $T_A = 25^\circ\text{C}$, $I_F = 0\text{ mA}$, $V_O > 2\text{ V}$, $V_{CM} = 1.5\text{ kV}$	15			kV/ μs
	Common Mode Transient Immunity at Low Level Output*4	CM_L	$V_{CC} = 5\text{ V}$, $R_L = 350\ \Omega$, $T_A = 25^\circ\text{C}$, $I_F = 7.5\text{ mA}$, $V_O < 0.8\text{ V}$, $V_{CM} = 1.5\text{ kV}$	15			kV/ μs

Notes: *1. Typical values at $T_A = 25^\circ\text{C}$.

*2. Because V_{OL} of 2 V or more may be output when the LED current is input and when output supply of $V_{CC} = 2.6$ V or less, it is important to confirm the characteristics (operation with the power supply on and off) during design, before using this device.

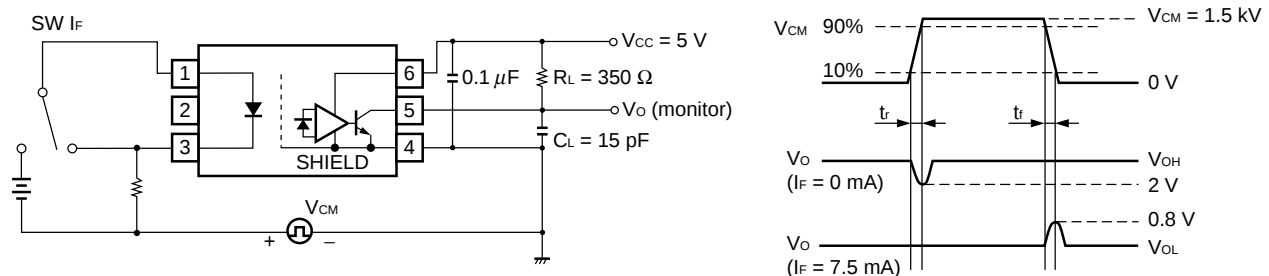
*3. Test circuit for propagation delay time

*4. V_{OH} is measured with the DC load current in this testing (Maximum pulse width = 2 ms, Maximum duty cycle = 20%).



Remark C_L includes probe and stray wiring capacitance.

*4 Test circuit for common mode transient immunity



Remark C_L includes probe and stray wiring capacitance.

USAGE CAUTIONS

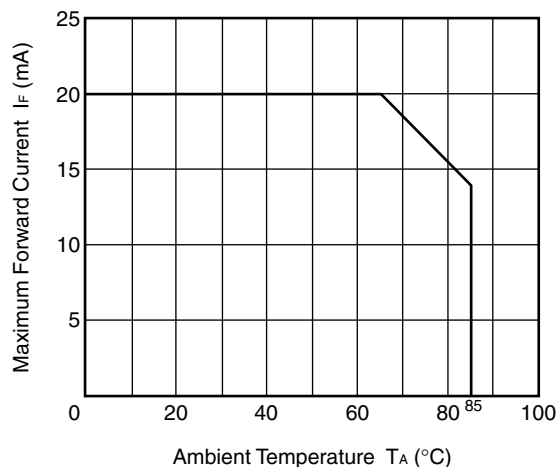
1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
2. By-pass capacitor of more than 0.1 μF is used between V_{CC} and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than 10 mm.
3. Pin 2 (which is an NC*1 pin) can either be connected directly to the GND pin on the LED side or left open. Unconnected pins should not be used as a bypass for signals or for any other similar purpose because this may degrade the internal noise environment of the device.

*1 NC: Not connected (No connection)

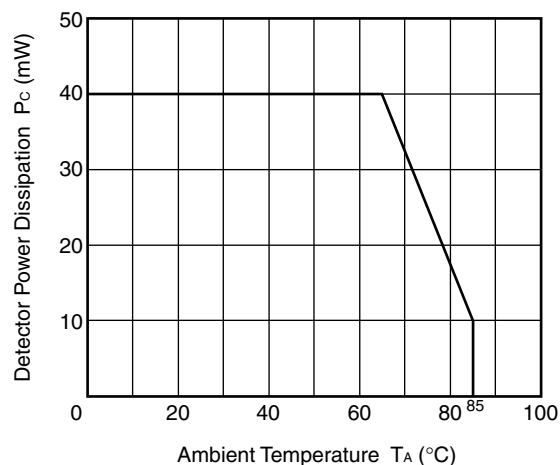
4. Avoid storage at a high temperature and high humidity.

TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

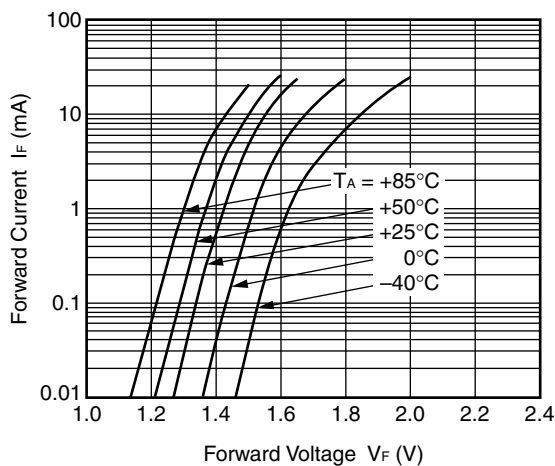
MAXIMUM FORWARD CURRENT vs. AMBIENT TEMPERATURE



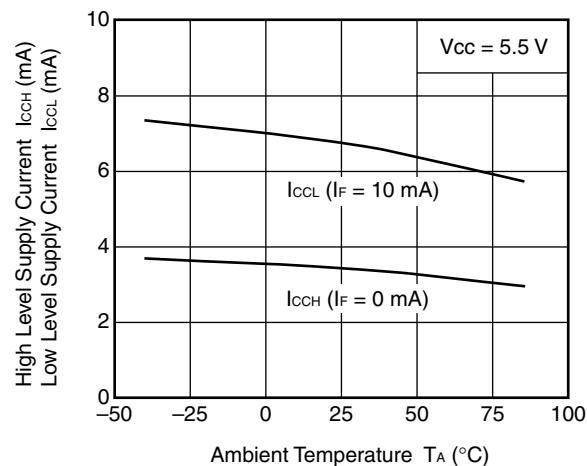
DETECTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



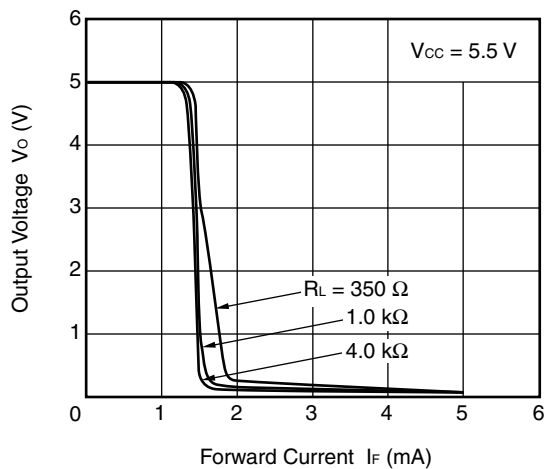
FORWARD CURRENT vs. FORWARD VOLTAGE



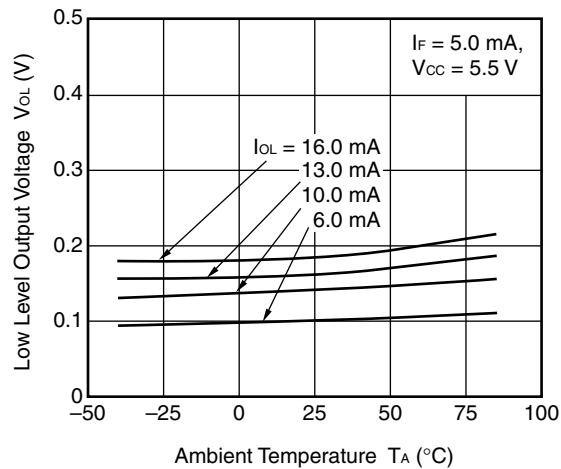
SUPPLY CURRENT vs. AMBIENT TEMPERATURE



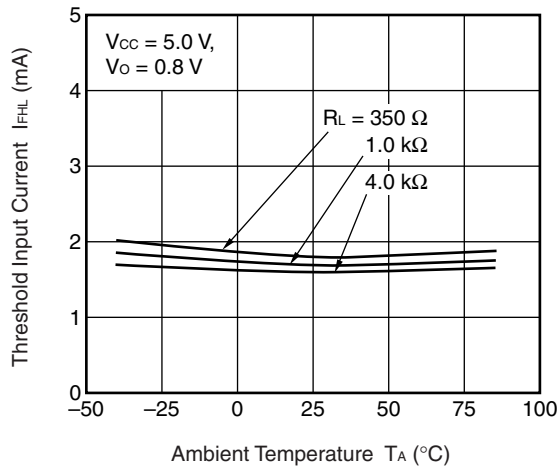
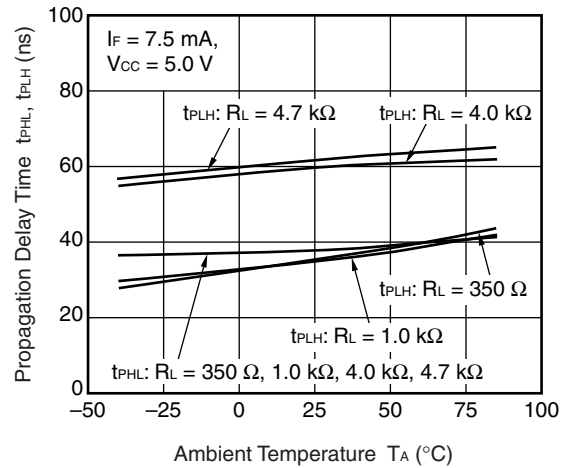
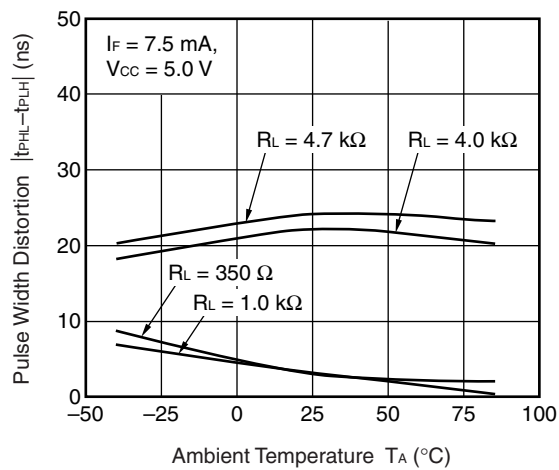
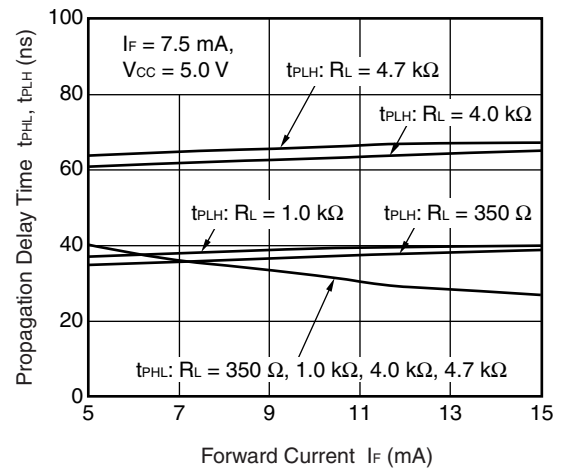
OUTPUT VOLTAGE vs. FORWARD CURRENT



LOW LEVEL OUTPUT VOLTAGE vs. AMBIENT TEMPERATURE



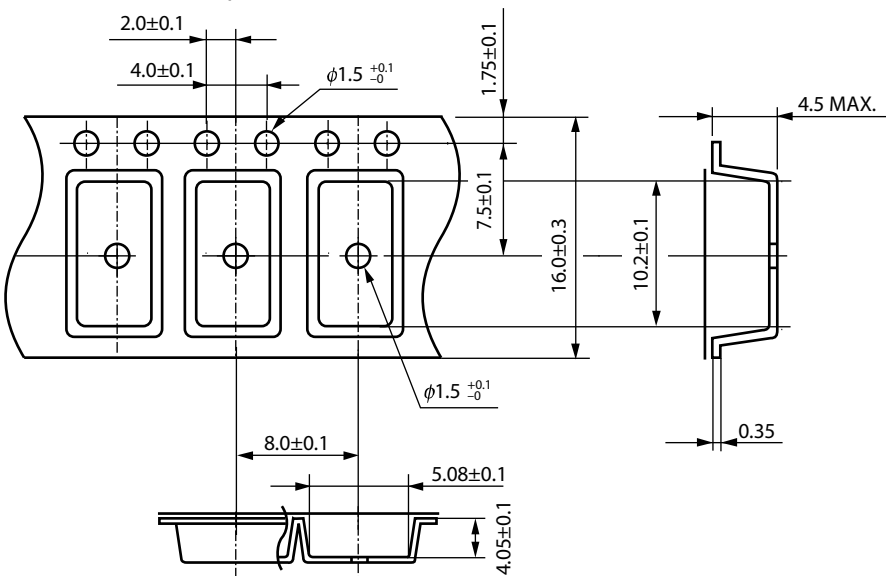
Remark The graphs indicate nominal characteristics.

THRESHOLD INPUT CURRENT vs.
AMBIENT TEMPERATUREPROPAGATION DELAY TIME vs.
AMBIENT TEMPERATUREPULSE WIDTH DISTORTION vs.
AMBIENT TEMPERATUREPROPAGATION DELAY TIME vs.
FORWARD CURRENT

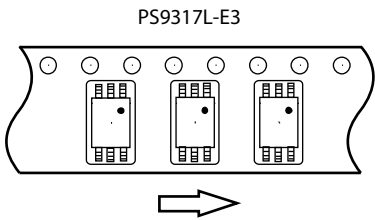
Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT: mm)

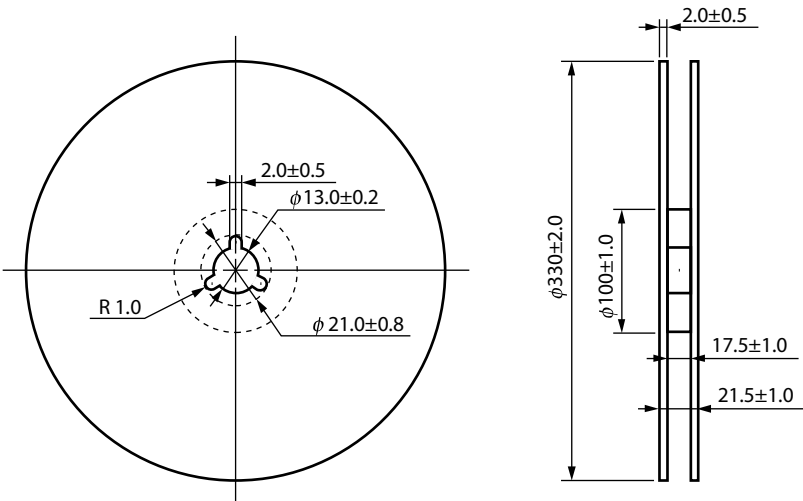
Outline and Dimensions (Tape)



Tape Direction

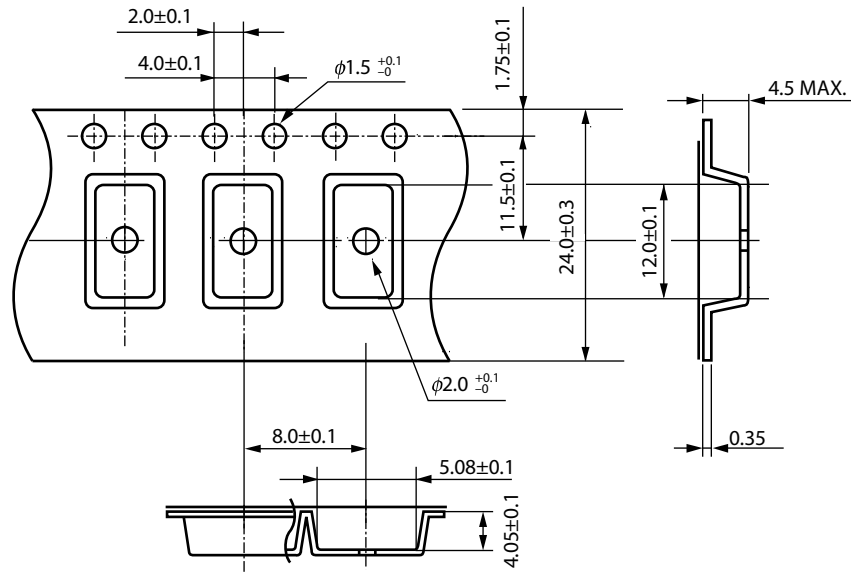


Outline and Dimensions (Reel)

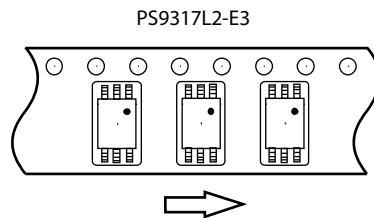


Packing: 2 000 pcs/reel

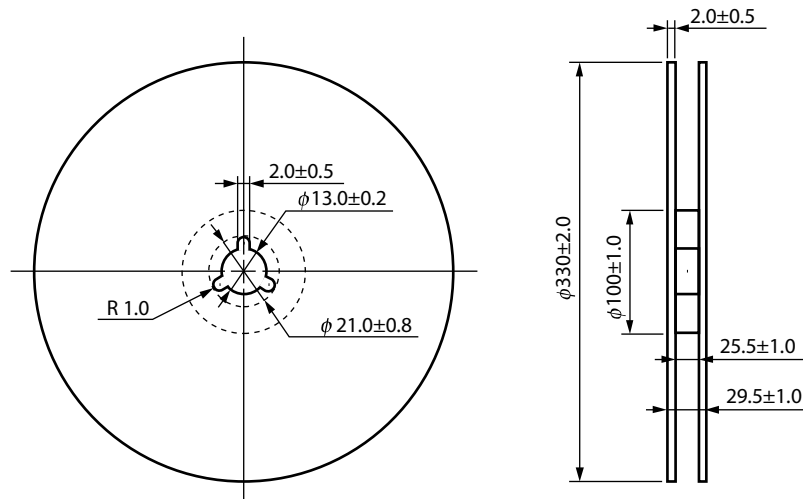
Outline and Dimensions (Tape)



Tape Direction

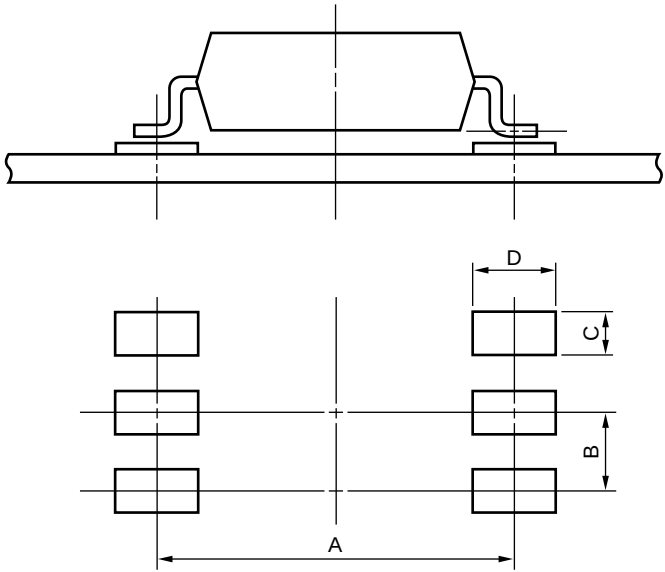


Outline and Dimensions (Reel)



Packing: 2 000 pcs/reel

RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



Part Number	Lead Bending	A	B	C	D
PS9317L	lead bending type (Gull-wing) for surface mount	8.2	1.27	0.8	2.2
PS9317L2	lead bending type (Gull-wing) for long creepage distance (surface mount)	10.2	1.27	0.8	2.2

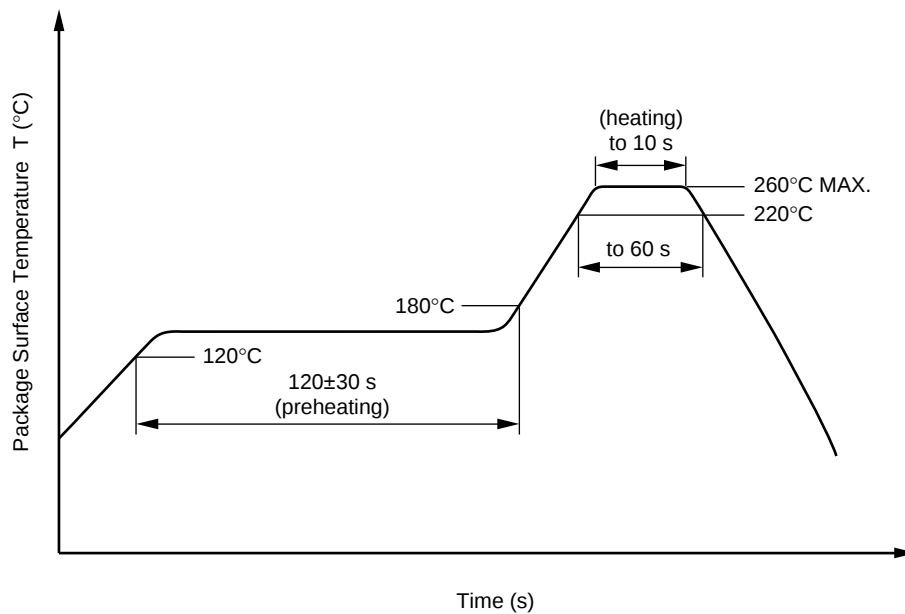
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

- | | |
|---|--|
| • Peak reflow temperature | 260°C or below (package surface temperature) |
| • Time of peak reflow temperature | 10 seconds or less |
| • Time of temperature higher than 220°C | 60 seconds or less |
| • Time to preheat temperature from 120 to 180°C | 120 ± 30 s |
| • Number of reflows | Three |
| • Flux | Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- | | |
|-------------------------|--|
| • Temperature | 260°C or below (molten solder temperature) |
| • Time | 10 seconds or less |
| • Preheating conditions | 120°C or below (package surface temperature) |
| • Number of times | One (Allowed to be dipped in solder including plastic mold portion.) |
| • Flux | Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

(3) Soldering by Soldering Iron

- | | |
|--|--|
| • Peak Temperature (lead part temperature) | 350°C or below |
| • Time (each pins) | 3 seconds or less |
| • Flux | Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

- Fluxes Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output side may enter the on state, even if the voltage is within the absolute maximum ratings.

SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Spec.	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		40/85/21	
Dielectric strength			
maximum operating isolation voltage	U_{IORM}	1 130	V_{peak}
Test voltage (partial discharge test, procedure a for type test and random test) $U_{pr} = 1.6 \times U_{IORM}$, $P_d < 5 \text{ pC}$	U_{pr}	1 808	V_{peak}
Test voltage (partial discharge test, procedure b for all devices) $U_{pr} = 1.875 \times U_{IORM}$, $P_d < 5 \text{ pC}$	U_{pr}	2 119	V_{peak}
Highest permissible overvoltage	U_{TR}	8 000	V_{peak}
Degree of pollution (DIN EN 60664-1 VDE0110 Part 1)		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303 Part 11))	CTI	175	
Material group (DIN EN 60664-1 VDE0110 Part 1)		III a	
Storage temperature range	T_{stg}	-55 to +125	°C
Operating temperature range	T_A	-40 to +85	°C
Isolation resistance, minimum value			
$V_{IO} = 500 \text{ V dc}$ at $T_A = 25^\circ\text{C}$	Ris MIN.	10^{12}	Ω
$V_{IO} = 500 \text{ V dc}$ at $T_A \text{ MAX.}$ at least 100°C	Ris MIN.	10^{11}	Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve)			
Package temperature	T_{si}	175	°C
Current (input current I_F , $P_{si} = 0$)	I_{si}	400	mA
Power (output or total power dissipation)	P_{si}	700	mW
Isolation resistance			
$V_{IO} = 500 \text{ V dc}$ at $T_A = T_{si}$	Ris MIN.	10^9	Ω

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
 1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

Revision History	PS9317L, PS9317L2 Data Sheet
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Rev.	Date	Description	
		Page	Summary
5.00	Oct 30, 2015	–	First edition issued

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